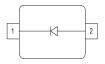


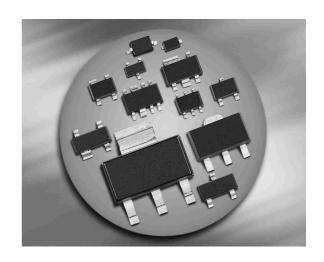
Silicon Variable Capacitance Diodes

- For VHF TV-tuners
- High capacitance ratio
- Low series inductance
- Low series resistance
- Excellent uniformity and matching due to "in-line" matching assembly procedure
- Pb-free (RoHS compliant) package



BB644 BB664/-02V





Туре	Package	Configuration	L S(nH)	Marking
BB644	SOD323	single	1.8	yellow 4
BB664	SCD80	single	0.6	44
BB664-02V	SC79	single	0.6	4

Maximum Ratings at $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage	V_{R}	30	V
Peak reverse voltage	V_{RM}	35	
$R \ge 5k\Omega$			
Forward current	I _F	20	mA
Operating temperature range	T_{op}	-55 150	°C
Storage temperature	$T_{ m stg}$	-55 150	



Electrical Characteristics at $T_A = 25$ °C, unless otherwise specified

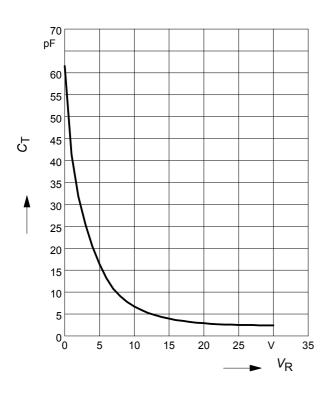
Parameter	Symbol		Unit		
		min.	typ.	max.	
DC Characteristics					
Reverse current	I_{R}				nA
<i>V</i> _R = 30 V		-	-	10	
$V_{\rm R}$ = 30 V, $T_{\rm A}$ = 85 °C		-	_	100	
AC Characteristics					
Diode capacitance	C_{T}				pF
$V_{R} = 1 \text{ V}, f = 1 \text{ MHz}$		39	41.8	44.5	
$V_{R} = 2 \text{ V}, f = 1 \text{ MHz}$		29.4	31.85	34.2	
$V_{R} = 25 \text{ V}, f = 1 \text{ MHz}$		2.5	2.7	2.85	
$V_{R} = 28 \text{ V}, f = 1 \text{ MHz}$		2.4	2.55	2.75	
Capacitance ratio	C _{T1} /C _{T28}	15	16.4	17.8	
V_{R} = 1 V, V_{R} = 28 V, f = 1 MHz					
Capacitance ratio	C _{T2} /C _{T25}	11	11.8	12.6	
$V_{R} = 2 \text{ V}, V_{R} = 25 \text{ V}, f = 1 \text{ MHz}$					
Capacitance matching ¹⁾	$\Delta C_{T}/C_{T}$	-	-	2	%
V_{R} = 1 28 V, f = 1 MHz, 7 diodes sequence					
Series resistance	r _S	_	0.6	0.75	Ω
V_{R} = 5 V, f = 470 MHz					

¹For details please refer to Application Note 047.

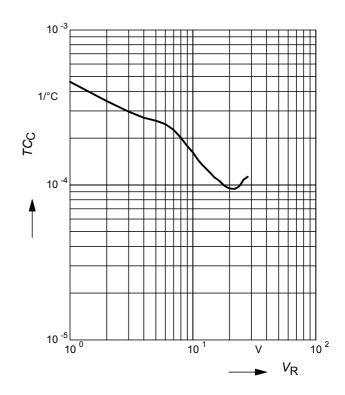


Diode capacitance $C_T = f(V_R)$

f = 1MHz

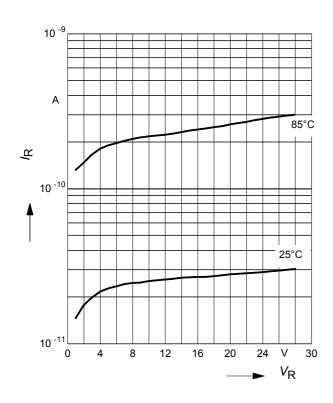


Temperature coefficient of the diode capacitance $T_{Cc} = f(V_R)$



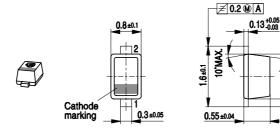
Reverse current $I_R = f(V_R)$

 T_A = Parameter





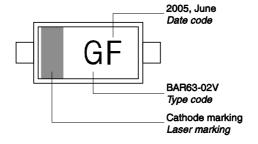
Package Outline



Foot Print



Marking Layout (Example)

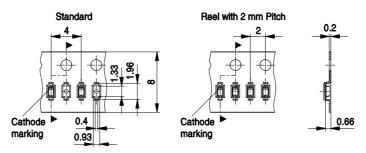


Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel

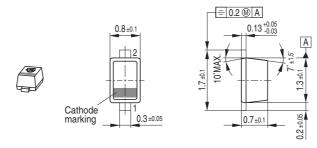
Reel ø180 mm = 8.000 Pieces/Reel (2 mm Pitch)

Reel ø330 mm = 10.000 Pieces/Reel





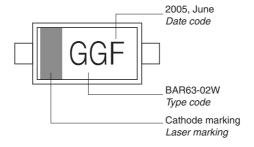
Package Outline



Foot Print



Marking Layout (Example)

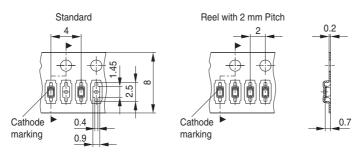


Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel

Reel ø180 mm = 8.000 Pieces/Reel (2 mm Pitch)

Reel ø330 mm = 10.000 Pieces/Reel





Date Code marking for discrete packages with one digit (SCD80, SC79, SC75¹⁾) CES-Code

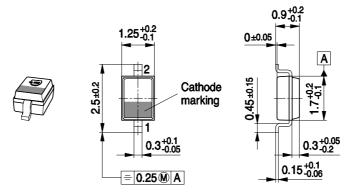
Month	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014
01	а	р	Α	Р	а	р	Α	Р	а	р	Α	Р
02	b	q	В	Q	b	q	В	Q	b	q	В	Q
03	С	r	С	R	С	r	С	R	С	r	С	R
04	d	S	D	S	d	S	D	S	d	S	D	S
05	е	t	Е	T	е	t	Е	Т	е	t	Е	Т
06	f	u	F	U	f	u	F	U	f	u	F	U
07	g	٧	G	V	g	٧	G	٧	g	٧	G	V
08	h	Х	Η	Х	h	Х	Η	Х	h	Х	Ι	Х
09	j	у	7	Υ	j	у	7	Υ	j	у	7	Υ
10	k	Z	K	Z	k	Z	K	Z	k	Z	K	Z
11	I	2	L	4	I	2	L	4	I	2	L	4
12	n	3	Ζ	5	n	3	Ν	5	n	3	Z	5

¹⁾ New Marking Layout for SC75, implemented at October 2005.

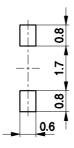
6 2011-06-15



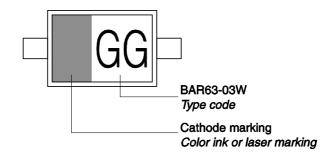
Package Outline



Foot Print

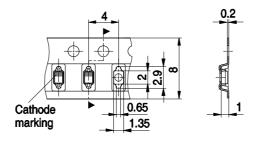


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel





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